

Title (en)

RESILIENT PROBES FOR ELECTRICAL TESTING

Title (de)

NACHGIEBIGE SONDEN ZUR ELEKTRISCHEN PRÜFUNG

Title (fr)

SONDES ELASTIQUES CONÇUES POUR ESSAIS ELECTRIQUES

Publication

**EP 2569646 A4 20140122 (EN)**

Application

**EP 06739525 A 20060323**

Priority

- US 66567605 P 20050328
- US 11688405 A 20050427
- US 2006010779 W 20060323

Abstract (en)

[origin: WO2006104886A2] An apparatus for electrical testing having probes (201) constructed of metal elements (201a) of about equal size bonded together in substantially linear sequence. Further an insulating holder (202) having first and second surfaces and a plurality of metal-filled vias (210) traversing the holder from the first to the second surface; the vias form contact pads on the first and second surfaces. The contact pads (210a) of the first holder surface have a probe attached so that the probe is positioned about normal to the surface. A sheet (203) of resilient insulating material, which has first and second surfaces and a thickness traversed by a plurality of conducting traces (220), has its first sheet surface attached to the second holder surface so that at least one of the traces contacts one of the contact pads, respectively, to provide an electrical path to the second sheet surface. A printed circuit board, suitable for insertion into an electrical test apparatus, is attached to the second sheet surface so that a continuous electrical path is established from the apparatus to each of the probes.

IPC 8 full level

**G01R 1/067** (2006.01); **G01R 1/073** (2006.01); **G01R 31/26** (2006.01); **H01L 21/66** (2006.01)

CPC (source: EP)

**G01R 1/06738** (2013.01); **G01R 1/06744** (2013.01); **G01R 1/07378** (2013.01); **G01R 1/07321** (2013.01); **G01R 3/00** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

**WO 2006104886 A2 20061005**; **WO 2006104886 A3 20070301**; EP 2569646 A2 20130320; EP 2569646 A4 20140122

DOCDB simple family (application)

**US 2006010779 W 20060323**; EP 06739525 A 20060323